



Material Content Data Sheet



Sales Product Name		BCX 52 H6327		Issued		20. July 2018			
MA#		MA001202516							
Package		PG-SOT89-4-3		Weight*		53.17 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.017	0.03		322		
	non noble metal	tin	7440-31-5	0.004	0.01		83		
	inorganic material	silicon	7440-21-3	0.209	0.39	0.43	3927	4332	
leadframe	inorganic material	silicon	7440-21-3	0.005	0.01		95		
	non noble metal	titanium	7440-32-6	0.025	0.05		474		
	non noble metal	chromium	7440-47-3	0.076	0.14		1423		
	non noble metal	copper	7440-50-8	25.112	47.23	47.43	472308	474300	
wire	non noble metal	copper	7440-50-8	0.049	0.09	0.09	924	924	
encapsulation	organic material	carbon black	1333-86-4	0.268	0.50		5040		
	plastics	epoxy resin	-	4.019	7.56		75599		
	inorganic material	silicondioxide	60676-86-0	22.509	42.34	50.40	423352	503991	
leadfinish	non noble metal	tin	7440-31-5	0.801	1.51	1.51	15071	15071	
plating	noble metal	silver	7440-22-4	0.073	0.14	0.14	1382	1382	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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